

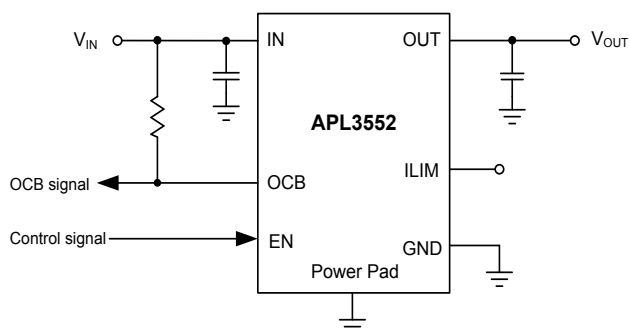
Features

- 62mΩ Power Switch On Resistance
- Wide Supply Voltage Range: 2.7V to 5.5V
- Adjustable Current Limit Protection
- Fast Over current Response: 2us (typ.)
- Over-Temperature Protection
- Fault Indication Output
- Reverse Input-Output Voltage Protection: 25mV (typ.)
- Enable Input
- Built-in Soft-Start
- UL Approved-File No. E328191
- UL-CB Scheme IEC/EN62368-1 Certified
- TUV IEC/EN62368-1 Certified

Applications

- Notebook and Desktop Computers
- USB Ports
- High-Side Power Protection Switches
- MHL Ports

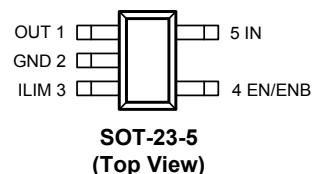
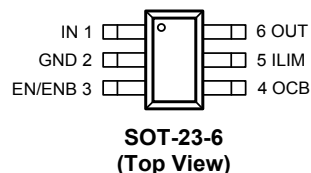
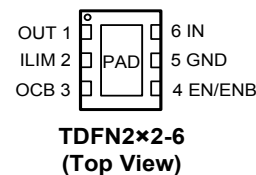
Simplified Application Circuit



General Description

The APL3552 series of power switches integrate a 62mΩ N-channel MOSFET power switch, an enable input pin, a fault flag and some protection functions into a single package. The protection features include adjustable current limit, reverse current protection, and over temperature protection. APL3552 offer an adjustable current-limit threshold between 150mA and 2.8A (typ.) via an external resistor. The reverse current protection disable the power switch when the output voltage is driven higher than the input to protect devices on the input side of the switch. The OCB output asserts low during over current and reverse current conditions. The over-temperature protection limits the junction temperature below 140°C in case of short circuit or over load conditions.

Pin Configuration



Ordering and Marking Information

APL3552 □□□-□□□ Assembly Material Handling Code Temperature Range Package Code EN Function	Package Code C: SOT-23-6 QB: TDFN2x2-6 B: SOT-23-5 Operating Ambient Temperature Range I: -40 to 85°C Handling Code TR: Tape & Reel EN Function A: EN Active High B: EN Active Low Assembly Material G: Halogen and Lead Free Device
APL3552 B: 52OX	X - Date Code O - EN Function Code
APL3552 C: 52OX	X - Date Code O - EN Function Code
APL3552 QB: L52O X	X - Date Code O - EN Function Code

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

Absolute Maximum Ratings (Note 1)

Symbol	Parameter	Rating	Unit
	Voltage range on IN, OUT, EN or ENB, ILIM, OCB to GND	-0.3 ~ 7	V
T _J	Maximum Junction Temperature	150	°C
T _{STG}	Storage Temperature	-65 ~ 150	°C
T _{SDR}	Maximum Lead Soldering Temperature, 10 Seconds	260	°C

Note1: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Thermal Characteristics (Note2)

Symbol	Parameter		Typical Value	Unit
θ_{JA}	Junction-to-Ambient Resistance in Free Air	SOT-23-5	260	°C/W
		SOT-23-6	250	
		TDFN2x2-6	75	

Note 2: θ_{JA} is measured with the component mounted on a high effective thermal conductivity test board in free air.

Recommended Operating Conditions (Note3)

Symbol	Parameter	Range	Unit
V _{IN}	IN Input Voltage	2.7 ~ 5.5	V
I _{OUT}	OUT Output Current	0 ~ 2	A
R _{ILIM}	Current-Limit Threshold Resistor Range	10 ~ 150	kΩ
T _A	Ambient Temperature	-40 ~ 85	°C
T _J	Junction Temperature	-40 ~ 125	°C

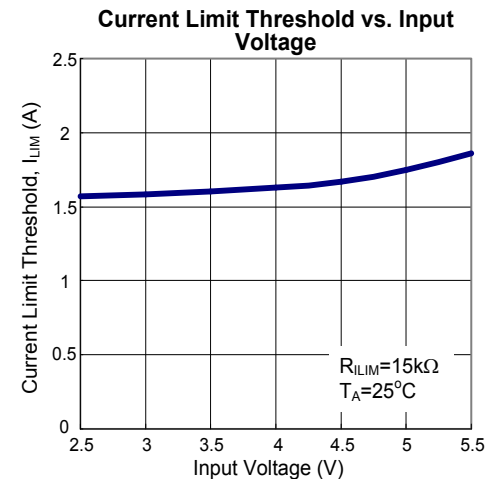
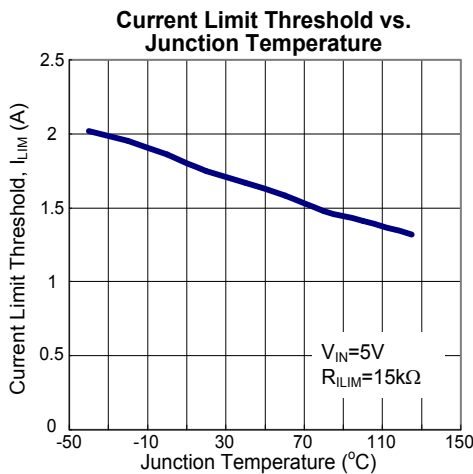
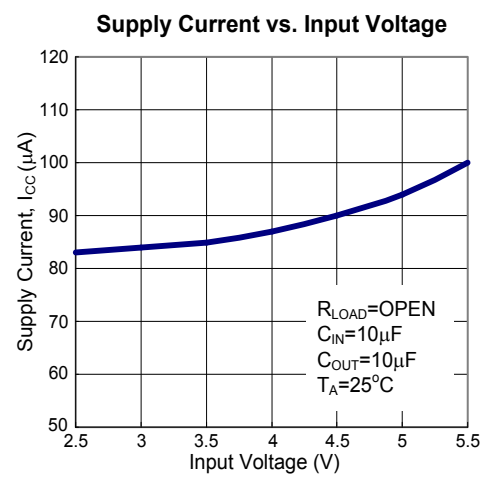
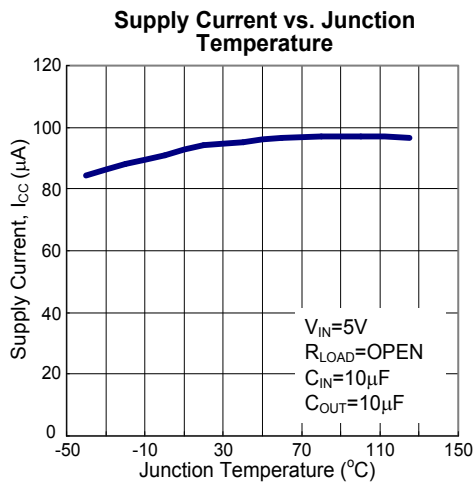
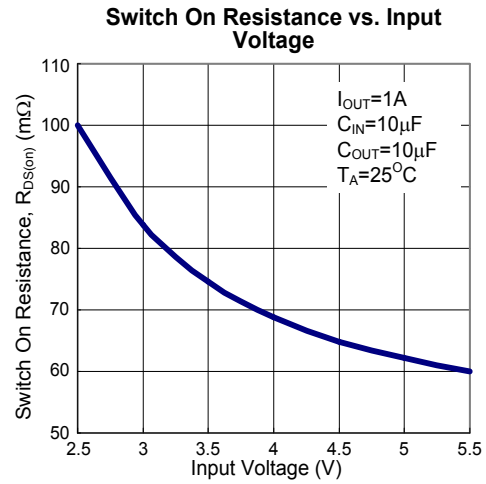
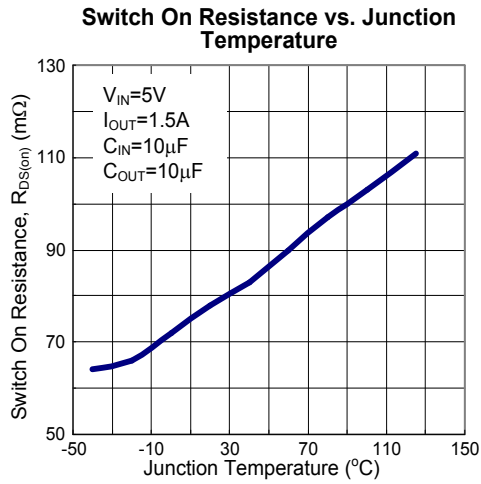
Note 3: Refer to the application circuit.

Electrical Characteristics

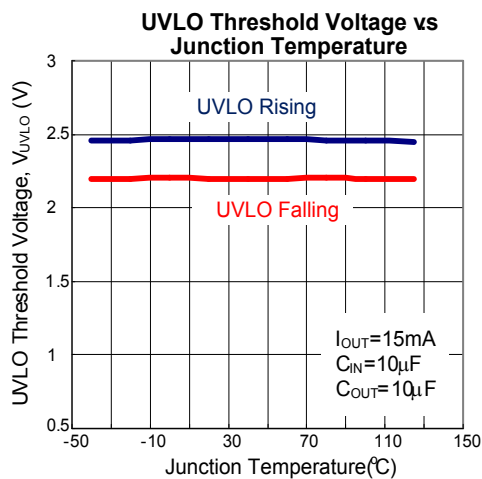
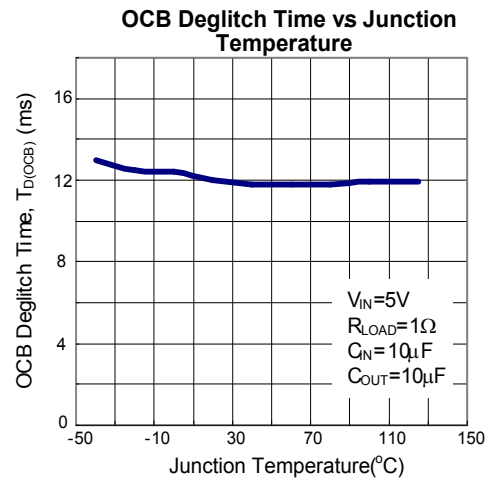
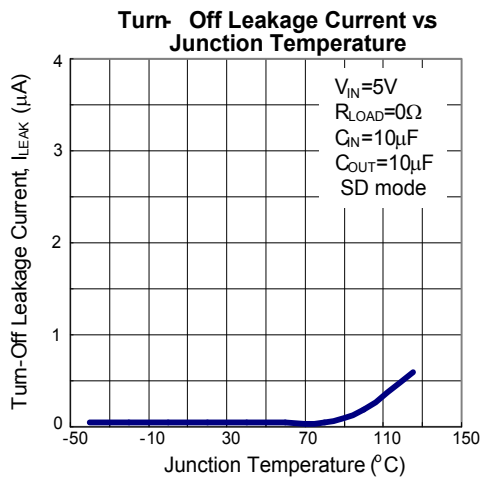
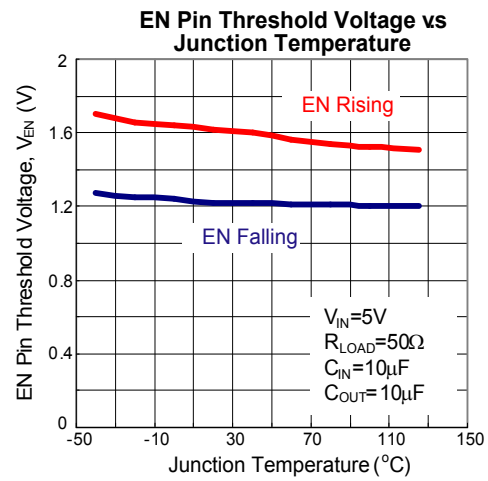
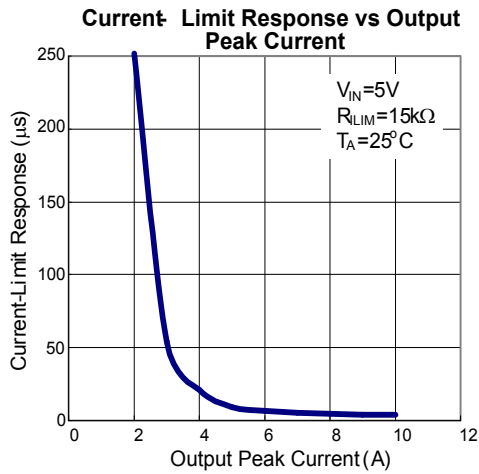
Unless otherwise specified, these specifications apply over $V_{IN}=5V$, $V_{EN}=5V$ or $V_{ENB}=0V$ and $T_A = -40$ to $85^{\circ}C$. Typical values are at $T_A=25^{\circ}C$.

Symbol	Parameter	Test Conditions	APL3552			Unit	
			Min.	Typ.	Max.		
SUPPLY CURRENT							
I _{IN}	IN Supply Current	NO load, V _{EN} =0V (For APL3552A)	-	-	1	uA	
		NO load, V _{ENB} =3V (For APL3552B)	-	-	3		
		NO load, V _{EN} =5V or V _{ENB} =0V, R _{ILIM} =20kΩ	-	100	150		
		NO load, V _{EN} =5V or V _{ENB} =0V R _{ILIM} Open	-	90	-		
	Leakage Current	OUT=GND, V _{EN} =0V or V _{ENB} =5V	-	-	1		
I _{REV}	Reverse Leakage Current	V _{OUT} =5V, V _{IN} =GND, V _{EN} =0V or V _{ENB} =5V	-	-	1		
POWER SWITCH							
R _{DS(ON)}	Power Switch On Resistance	I _{OUT} =1A, T _A = 25°C	—	62	78	mΩ	
UNDER-VOLTAGE LOCKOUT(UVLO)							
	VIN UVLO Threshold Voltage	V _{IN} rising, T _A = -40 ~ 85°C	1.7	-	2.65	V	
	VIN UVLO Hysteresis		-	0.2	-		
CURRENT LIMIT							
	Maximum Current-limit set point	R _{ILIM} =10k	2.1	2.8	3.2	A	
I _{LIM}	Current Limit Threshold	V _{IN} =2.7V to 5.5V, T _A = -40 ~ 85°C	R _{ILIM} =15kΩ	1.4	1.7	2	A
			R _{ILIM} =20kΩ	1.101	1.295	1.489	
			R _{ILIM} =49.9kΩ	0.442	0.52	0.598	
			R _{ILIM} =150kΩ	0.11	0.15	0.2	
T _{IOS}	Response time of over current	V _{IN} = 5V	-	2	-	us	
	ILIM voltage source	V _{IN} =2.7V to 5.5V	0.38	0.4	0.42	V	
OCB OUTPUT PIN							
V _{OCB}	OCB Output Low Voltage	I _{OCB} =5mA	-	0.2	0.4	V	
I _{OCB}	OCB Leakage Current	V _{OCB} =5V	-	-	1	uA	
T _{D(OCB)}	OCB Deglitch Time	OCB assertion, T _A =-40~85°C	5	12	20	ms	
REVERSE VOLTAGE PROTECT							
I _{REV}	Reverse current trip point	Enable reverse current protection	-	100	-	mA	
V _{REV}	Reverse voltage comparator trip point	V _{IN} -V _{OUT} , disable reverse current protection	-	25	-	mV	
T _{REV}	Time from reverse current condition to MOSFET turn off	V _{IN} =5V	3	5	7	ms	
EN or ENB INPUT PIN							
V _{IH}	Input Logic High	V _{IN} =2.7V to 5.5V	1.4	-	-	V	
V _{IL}	Input Logic Low	V _{IN} =2.7V to 5.5V	-	-	0.6		
I _{EN}	EN Input Current		-	-	1	uA	
T _{D(ON)}	Turn on Delay Time		-	80	-	us	
T _{D(OFF)}	Turn off Delay Time		-	5	-		
T _{SS}	Soft Start Time	No Load, C _{OUT} =1uF, V _{IN} =5V	-	400	1000		
	V _{OUT} Discharge Resistance	V _{EN} =0V or V _{ENB} =5V	-	150	-		Ω
OVERT-TEMPERATURE PROTECTION (OTP)							
T _{OTP}	Over-Temperature Threshold	T _J rising	-	140	-	°C	
	Over-Temperature Hysteresis		-	20	-		

Typical Operating Characteristics

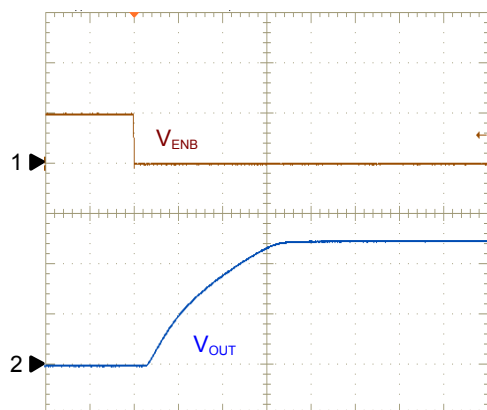


Typical Operating Characteristics(Cont.)



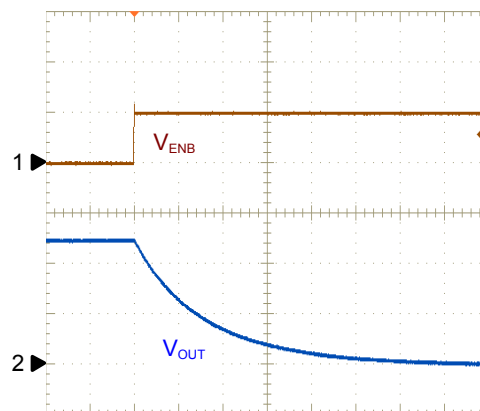
Operating Waveforms

Turn On Response



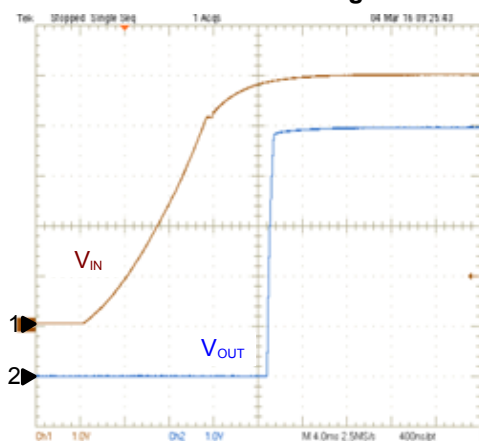
$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LOAD}=30\Omega$
 CH1: $V_{ENB}, 5V/\text{Div}, \text{DC}$
 CH2: $V_{OUT}, 2V/\text{Div}, \text{DC}$
 TIME: $200\mu s/\text{Div}$

Turn Off Response



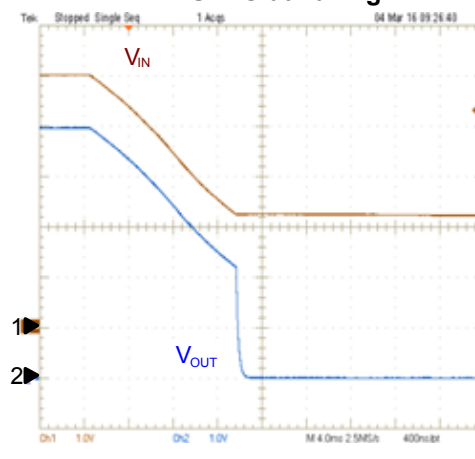
$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LOAD}=30\Omega$
 CH1: $V_{ENB}, 5V/\text{Div}, \text{DC}$
 CH2: $V_{OUT}, 2V/\text{Div}, \text{DC}$
 TIME: $100\mu s/\text{Div}$

UVLO at Rising



$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LOAD}=30\Omega$
 CH1: $V_{IN}, 1V/\text{Div}, \text{DC}$
 CH2: $V_{OUT}, 1V/\text{Div}, \text{DC}$
 TIME: $4ms/\text{Div}$

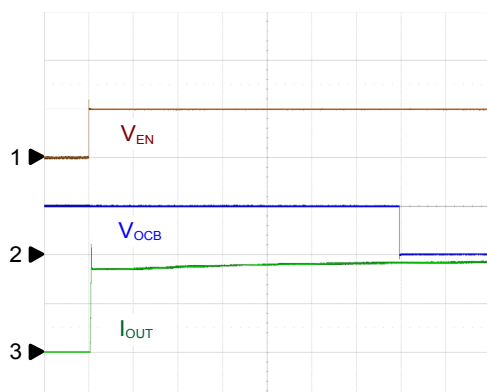
UVLO at Falling



$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LOAD}=30\Omega$
 CH1: $V_{IN}, 1V/\text{Div}, \text{DC}$
 CH2: $V_{OUT}, 1V/\text{Div}, \text{DC}$
 TIME: $4ms/\text{Div}$

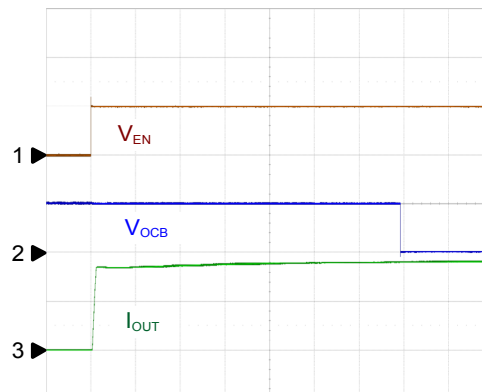
Operating Waveforms (Cont.)

OCB Response During Short Circuit



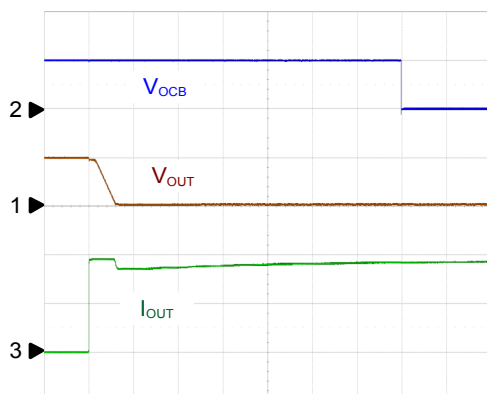
$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LIM}=15k\Omega, R_{LOAD}=0\Omega$
 CH1: $V_{EN}, 5V/\text{Div}, \text{DC}$
 CH2: $V_{OCB}, 5V/\text{Div}, \text{DC}$
 CH3: $I_{OUT}, 1A/\text{Div}, \text{DC}$
 TIME: $2ms/\text{Div}$

OCB Response During Over Load



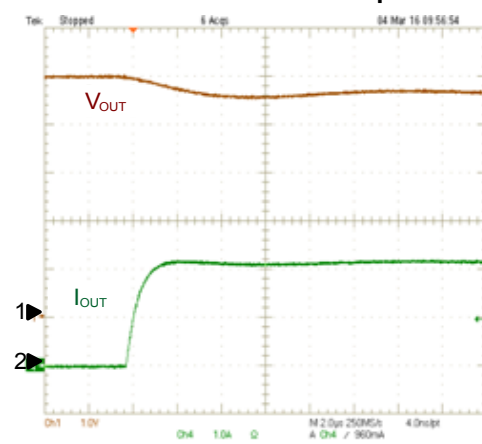
$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LIM}=15k\Omega, R_{LOAD}=1\Omega$
 CH1: $V_{EN}, 5V/\text{Div}, \text{DC}$
 CH2: $V_{OCB}, 5V/\text{Div}, \text{DC}$
 CH3: $I_{OUT}, 1A/\text{Div}, \text{DC}$
 TIME: $2ms/\text{Div}$

OCB Response with Ramped Load



$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, R_{LIM}=15k\Omega$
 CH1: $V_{OUT}, 5V/\text{Div}, \text{DC}$
 CH2: $V_{OCB}, 5V/\text{Div}, \text{DC}$
 CH3: $I_{OUT}, 1A/\text{Div}, \text{DC}$
 TIME: $2ms/\text{Div}$

Load- Transient Response



$V_{IN}=5V, C_{OUT}=10\mu F/\text{Electrolytic},$
 $C_{IN}=10\mu F/\text{Electrolytic}, I_{OUT}=0 \text{ to } 2A$
 CH1: $V_{OUT}, 1V/\text{Div}, \text{DC}$
 CH2: $I_{OUT}, 1A/\text{Div}, \text{DC}$
 TIME: $2\mu s/\text{Div}$

PIN			NAME	FUNCTION
NO.				
TDFN2x2-6	SOT-23-6	SOT-23-5		
1	6	1	VOUT	Output Voltage Pin. The output voltage follows the input voltage. When the device is enable.
2	5	3	ILIM	External resistor used to set current-limit threshold.
3	4	-	OCB	Fault Indication Pin. This pin goes low when a current limit or a reverse voltage condition is detected after a 12ms deglitch time.
4	3	4	EN (52A)	Enable Input. Pulling this pin to high will enable the device and pulling this pin to low will disable device. The EN pin cannot be left floating.
			ENB (52B)	Enable Input. Pulling this pin to high will disable the device and pulling this pin to low will enable device. The ENB pin cannot be left floating.
5	2	2	GND	Ground.
6	1	5	IN	Power Supply Input. Connect this pin to external DC supply.

The block diagram illustrates the internal architecture of the L6920B motor driver. It features an input terminal (IN) and an output terminal (OUT). The input stage includes a UVLO (Under-Voltage Lockout) block and a Charge Pump. The output stage consists of a MOSFET driver circuit controlled by the Gate Driver and Control Logic. This logic block receives inputs from the EN/ENB pin, the UVLO block, the Charge Pump, and an OTP (One-Time Programmable) memory. The output stage also includes a Reverse Voltage Protect block, a Current Limit block, a 5ms Deglitch block, and a 2us Response block. The output terminal (OUT) is connected to the motor load, which is represented by a resistor and an inductor. The output current is monitored by a current sense (CS) resistor, which is connected to the ILIM (Current Limit) pin. The OCB (Over-Current Protection) pin is also connected to the output stage. The GND pin is connected to the common ground.

Parameter Measurement Information

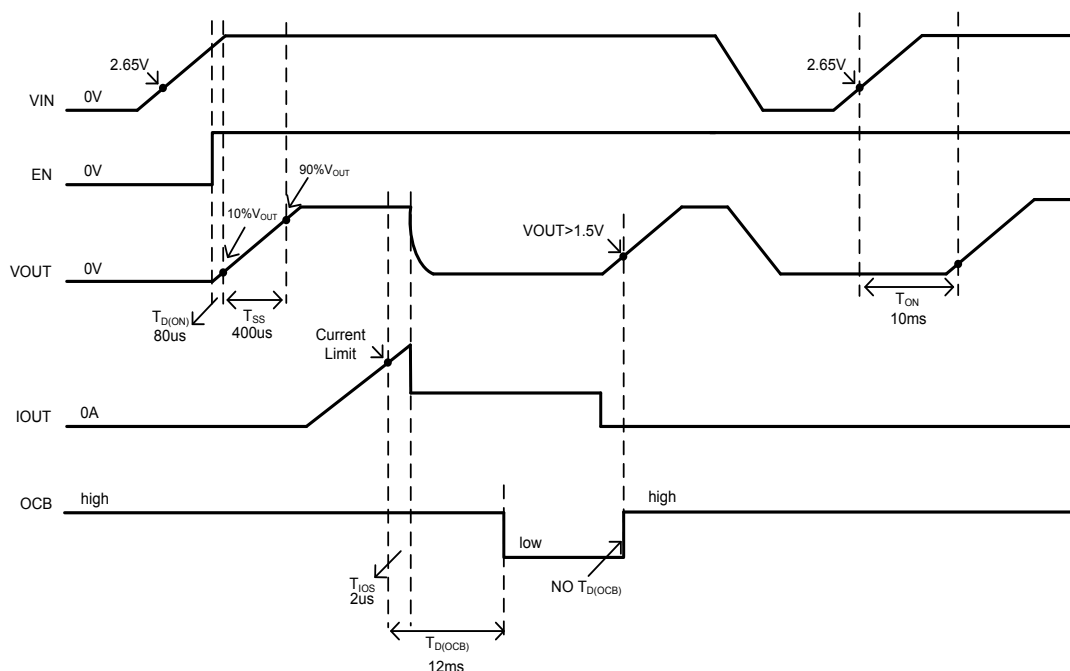


Figure 1. Sequence of Power On & Current Limit & OCB Indicate

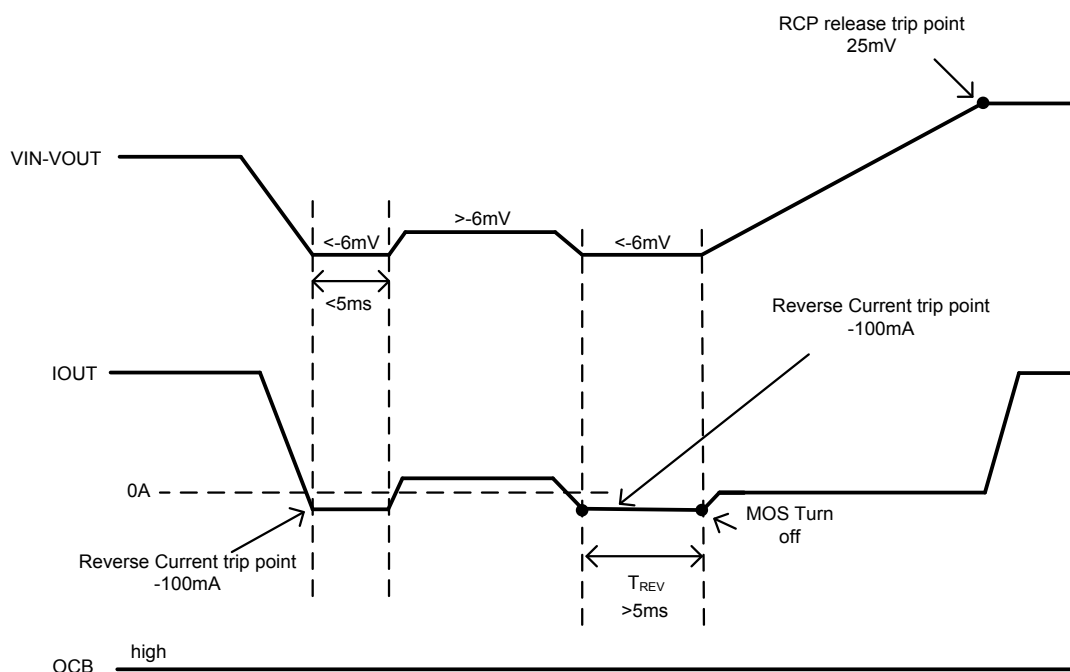
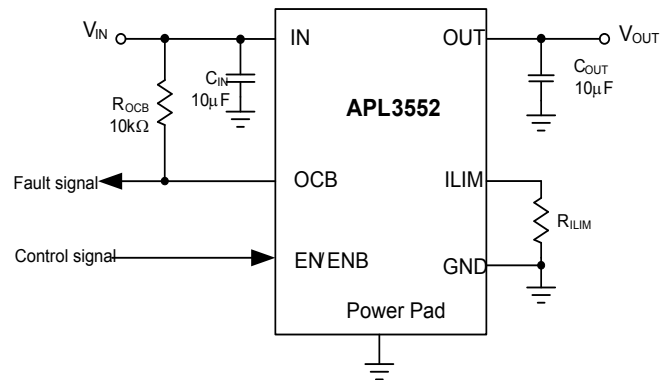


Figure 2. Reverse Current trip point & Recovery

Typical Application Circuit



Function Descriptions

VIN Under-Voltage Lockout (UVLO)

The APL3552 series of power switches have a built-in under-voltage lockout circuit to keep the output shutting off until internal circuitry is operating properly. The UVLO circuit has hysteresis and a de-glitch feature so that it will typically ignore undershoot transients on the input. When input voltage exceeds the UVLO threshold, the output voltage starts a soft-start to reduce the inrush current.

Power Switch

The power switch is an N-channel MOSFET with a low $R_{DS(ON)}$. The internal power MOSFET does not have the body diode. When IC is off, the MOSFET prevents a current flowing from the VOUT back to VIN and VIN to VOUT.

OCB Output

The APL3552 series of power switches provide an opendrain output to indicate that a fault has occurred. When any of current-limit or over-temperature protection occurs for a deglitch time of $t_{D(OCB)}$, the OCB goes low. If fault condition release, OCB will goes high when VOUT > 1.5V (see Figure 1). Since the OCB pin is an open-drain output, connecting a resistor to a pull high voltage is necessary.

Enable/Disable

Pull the ENB above 1.4V or EN below 0.6V will disable the device, and pull ENB pin below 0.6V or EN above 1.4V will enable the device. When the IC is disabled, the supply current is reduced to less than 1uA. The enable input is compatible with both TTL and CMOS logic levels. The EN/ENB pin cannot be left floating.

Reverse-Voltage Protection

The reverse voltage protection feature turns off the Nchannel MOSFET when a reverse current of $(VOUT - VIN)/R_{DS(on)}$ over 100mA(typ.) for 5ms (typ) deglitch time(see Figure 2). The APL3552 device allows the N-channel MOSFET immediately turn on once the output voltage goes lower than the input voltage by 25 mV (typ)(see Figure 2). This prevents damage to devices on the input side of the APL3552 by preventing significant current from sinking into the input capacitance.

Over-Temperature Protection

When the junction temperature exceeds 140°C, the internal thermal sense circuit turns off the power FET and allows the device to cool down. When the device's junction temperature cools by 20°C, the internal thermal sense circuit will enable the device, resulting in a pulsed output during continuous thermal protection. Thermal protection is designed to protect the IC in the event of over temperature conditions. For normal operation, the junction temperature cannot exceed $T_J=+125^{\circ}\text{C}$.

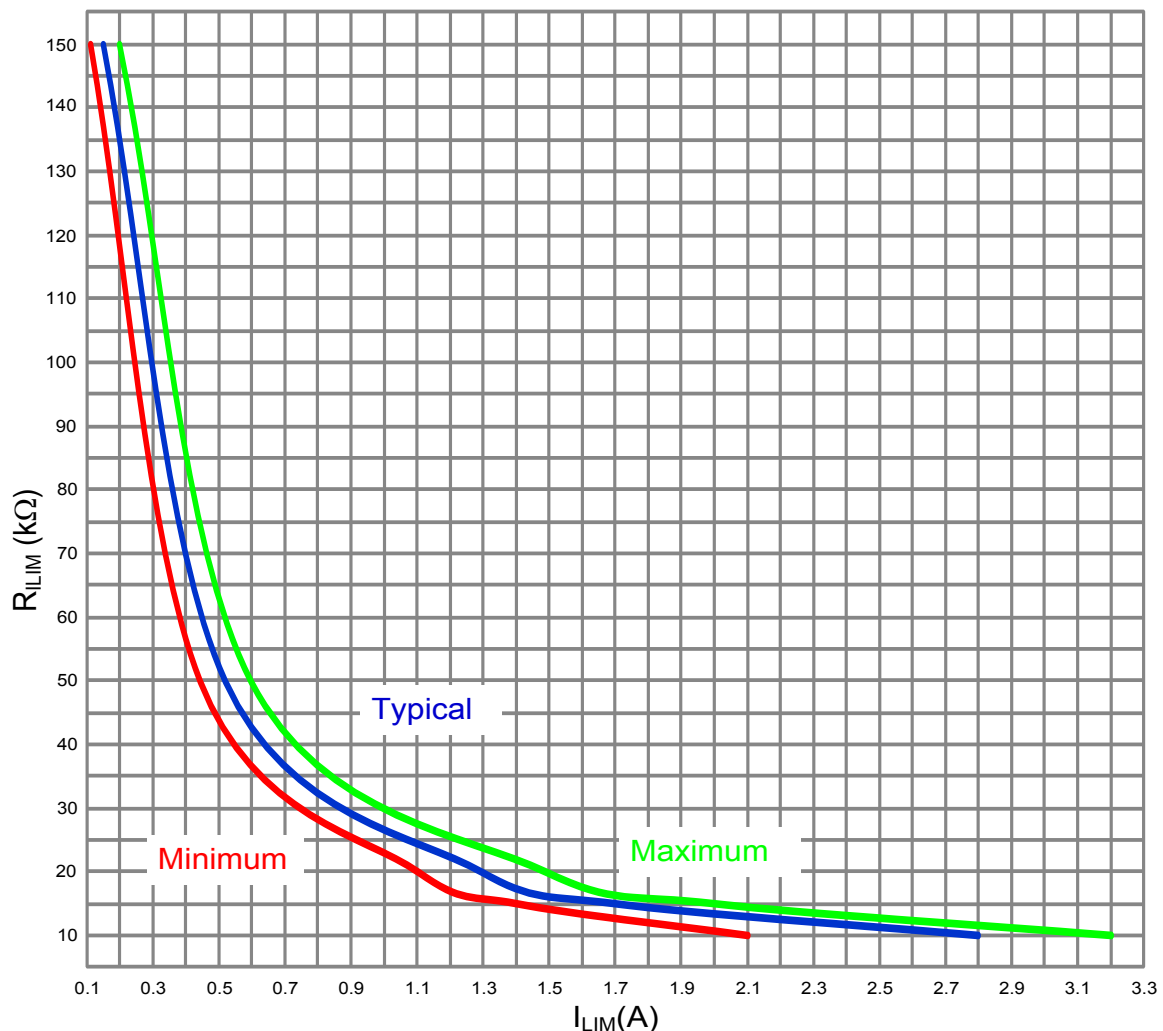
Function Descriptions (Cont.)

Current-Limit Protection

The APL3552 series of power switches provide the current-limit protection function. The adjustable current limit threshold of APL3552 is user programmable via an external resistor. The recommended 1% resistor range for R_{ILIM} is $10k\Omega < R_{ILIM} < 150k\Omega$ to ensure stability of the internal regulation loop.

While the maximum recommend value of R_{ILIM} is $150k\Omega$, there is one additional configuration that allows for a lower current-limit threshold. During current limit, the devices limit output current at current limit threshold. For reliable operation, the device should not be operated in current limit for extended period.

Current Limit vs. R_{ILIM}



Application Information

Input Capacitor

A 10uF ceramic bypass capacitor from IN to GND, located near the APL3552, is strongly recommended to suppress the ringing during short circuit fault event. Without the bypass capacitor, the output short may cause sufficient ringing on the input (from supply lead inductance) to damage internal control circuitry. Additional low-ESR ceramic capacitance may be necessary from IN to GND to prevent unwanted noise from coupling into the sensitive ILIM circuitry.

Output Capacitor

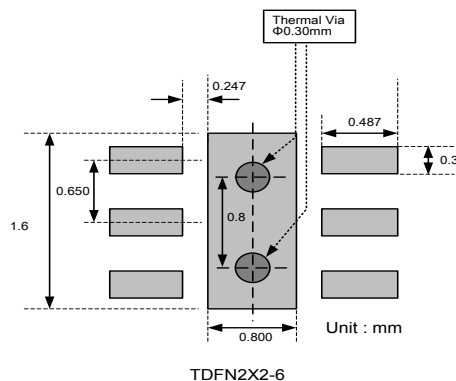
A low-ESR 150uF aluminum electrolytic between OUT and GND is strongly recommended to reduce the voltage droop during hot-attachment of downstream peripheral. Higher-value output capacitor is better when the output load is heavy. Additionally, bypassing the output with a 0.1uF ceramic capacitor improves the immunity of the device to short-circuit transients.

Layout Consideration

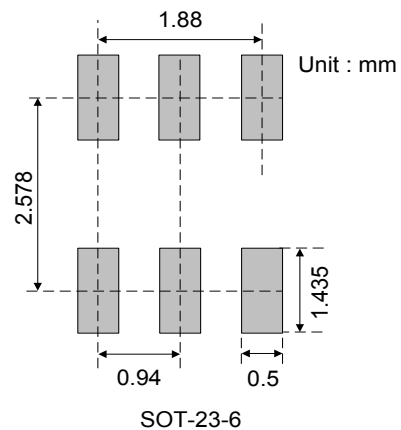
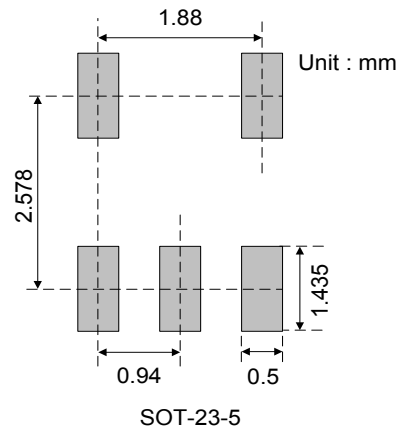
The PCB layout should be carefully performed to maximize thermal dissipation and to minimize voltage drop, droop and EMI. The following guidelines must be considered:

1. Please place the input capacitors near the IN pin as close as possible.
2. Output decoupling capacitors for load must be placed near the load as close as possible for decoupling high frequency ripples.
3. Locate APL3552 and output capacitors near the load to reduce parasitic resistance and inductance for excellent load transient performance.
4. The negative pins of the input and output capacitors and the GND pin must be connected to the ground plane of the load.
5. Keep IN and OUT traces as wide and short as possible.
6. The traces routing the R_{ILIM} resistor to the APL3552 should be as short as possible to reduce parasitic effects on the current limit accuracy.

Recommended Minimum Footprint

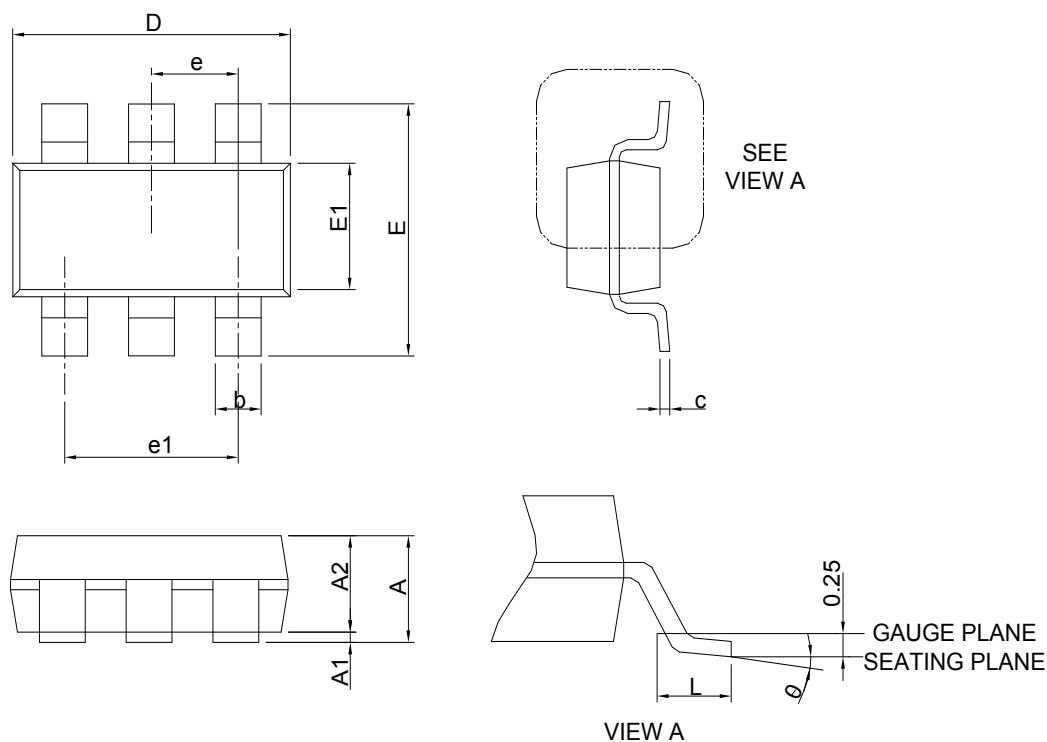


Recommended Minimum Footprint (Cont.)



Package Information

SOT-23-6

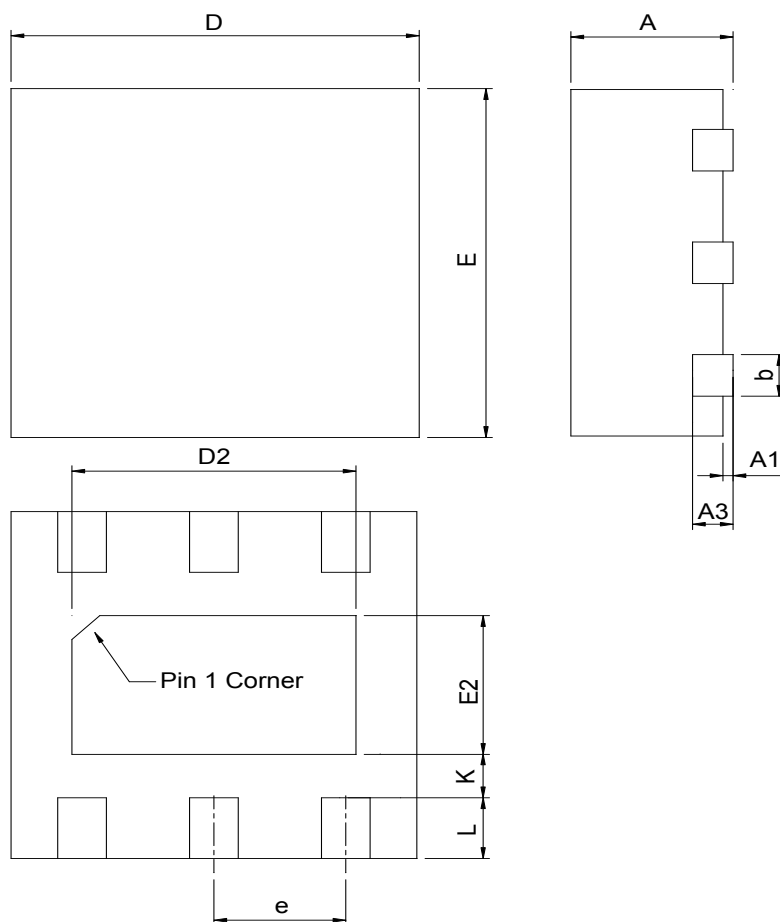


SYMBOL	SOT-23-6			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.45		0.057
A1	0.00	0.15	0.000	0.006
A2	0.90	1.30	0.035	0.051
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.70	3.10	0.106	0.122
E	2.60	3.00	0.102	0.118
E1	1.40	1.80	0.055	0.071
e	0.95 BSC		0.037 BSC	
e1	1.90 BSC		0.075 BSC	
L	0.30	0.60	0.012	0.024
θ	0°	8°	0°	8°

- Note : 1. Follow JEDEC TO-178 AB.
 2. Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

Package Information

TDFN2x2-6

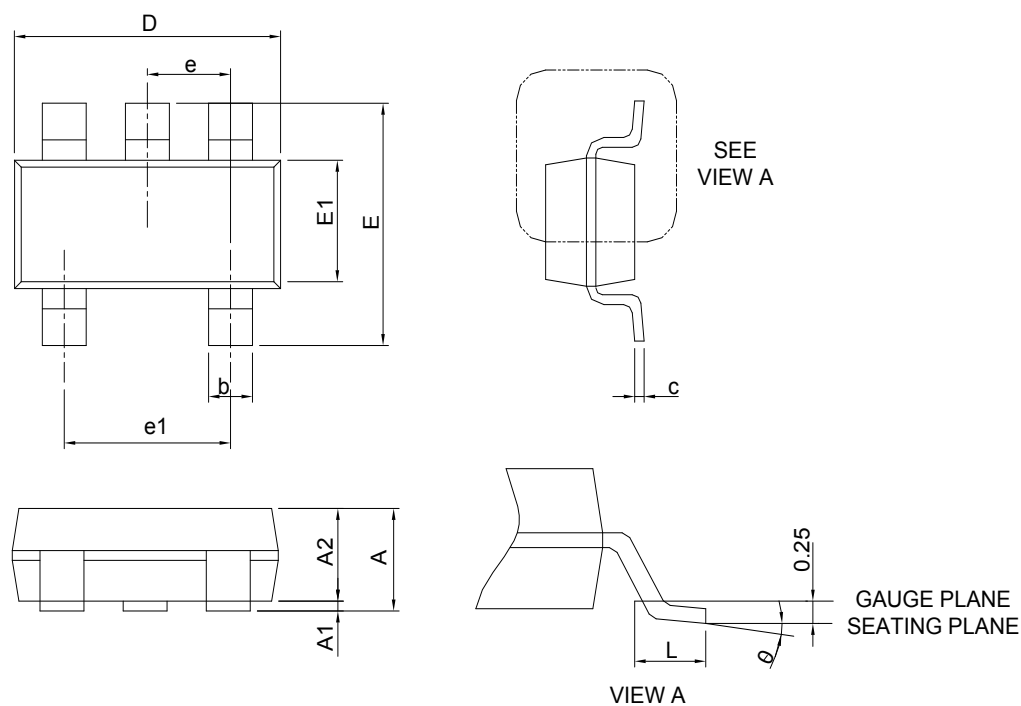


SYMBOL	TDFN2x2-6			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.20 REF		0.008 REF	
b	0.18	0.30	0.007	0.012
D	1.90	2.10	0.075	0.083
D2	1.00	1.60	0.039	0.063
E	1.90	2.10	0.075	0.083
E2	0.60	1.00	0.024	0.039
e	0.65 BSC		0.026 BSC	
L	0.30	0.45	0.012	0.018
K	0.20		0.008	

Note : 1. Followed from JEDEC MO-229 WCCC.

Package Information

SOT-23-5

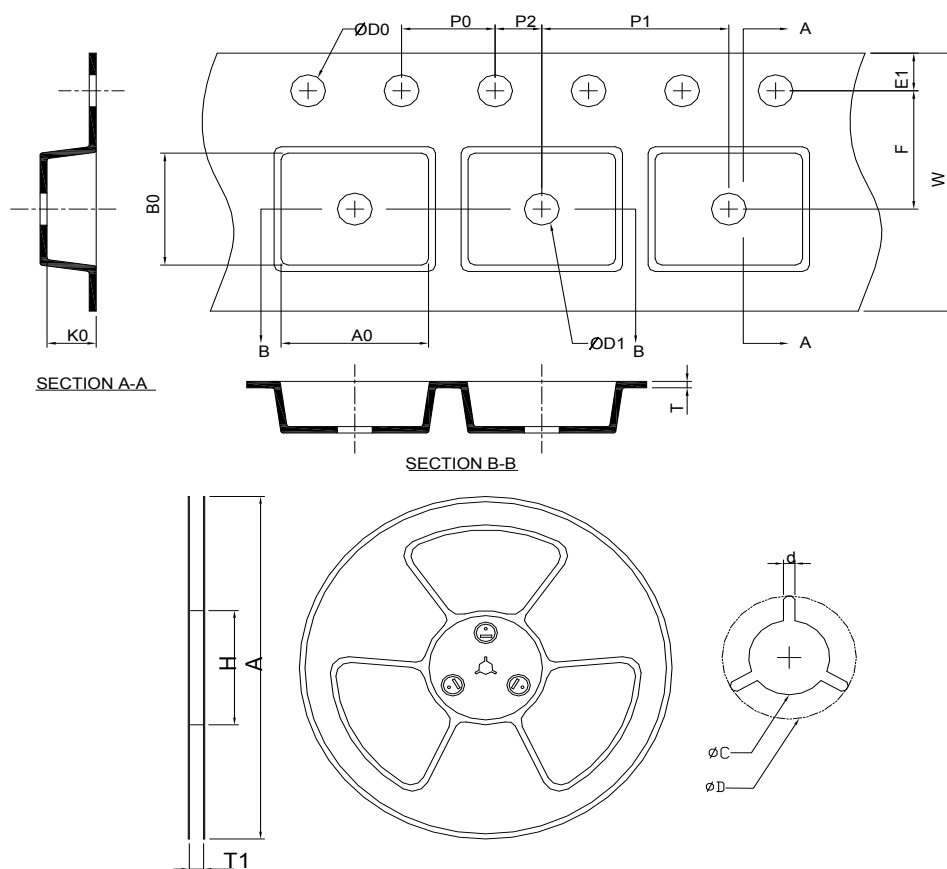


SYMBOL	SOT-23-5			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A		1.45		0.057
A1	0.00	0.15	0.000	0.006
A2	0.90	1.30	0.035	0.051
b	0.30	0.50	0.012	0.020
c	0.08	0.22	0.003	0.009
D	2.70	3.10	0.106	0.122
E	2.60	3.00	0.102	0.118
E1	1.40	1.80	0.055	0.071
e	0.95 BSC		0.037 BSC	
e1	1.90 BSC		0.075 BSC	
L	0.30	0.60	0.012	0.024
θ	0°	8°	0°	8°

Note : 1. Follow JEDEC TO-178 AA.

2. Dimension D and E1 do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.

Carrier Tape & Reel Dimensions



Application	A	H	T1	C	d	D	W	E1	F
SOT-23-6	178.0±2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0±0.30	1.75±0.10	3.5±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10 -0.00	1.0 MIN.	0.6+0.00 -0.40	3.20±0.20	3.10±0.20	1.50±0.20
Application	A	H	T1	C	d	D	W	E1	F
TDFN2x2-6	178.0±2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0±0.20	1.75±0.10	3.5±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10 -0.00	1.5 MIN.	0.6+0.00 -0.40	2.35±0.20	2.35±0.20	1.00±0.20
Application	A	H	T1	C	d	D	W	E1	F
SOT-23-5	178.0±2.00	50 MIN.	8.4+2.00 -0.00	13.0+0.50 -0.20	1.5 MIN.	20.2 MIN.	8.0±0.30	1.75±0.10	3.5±0.05
	P0	P1	P2	D0	D1	T	A0	B0	K0
	4.0±0.10	4.0±0.10	2.0±0.05	1.5+0.10 -0.00	1.0 MIN.	0.6+0.00 -0.40	3.20±0.20	3.10±0.20	1.50±0.20

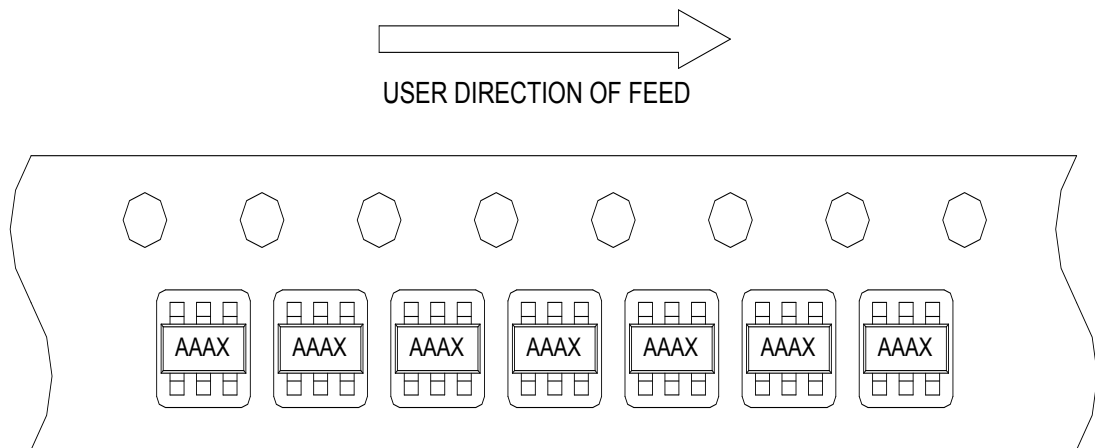
(mm)

Devices Per Unit

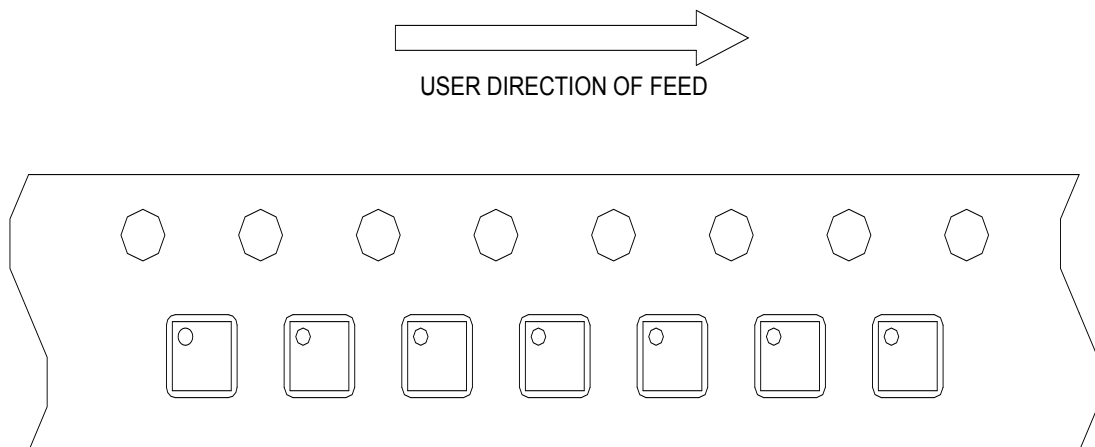
Package Type	Unit	Quantity
SOT-23-6	Tape & Reel	3000
TDFN2x2-6	Tape & Reel	3000
SOT-23-5	Tape & Reel	3000

Taping Direction Information

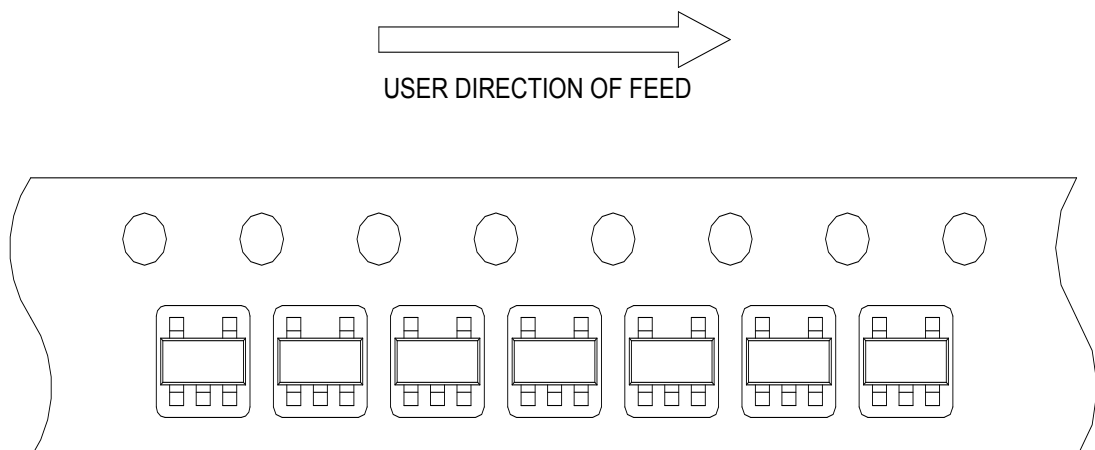
SOT-23-6



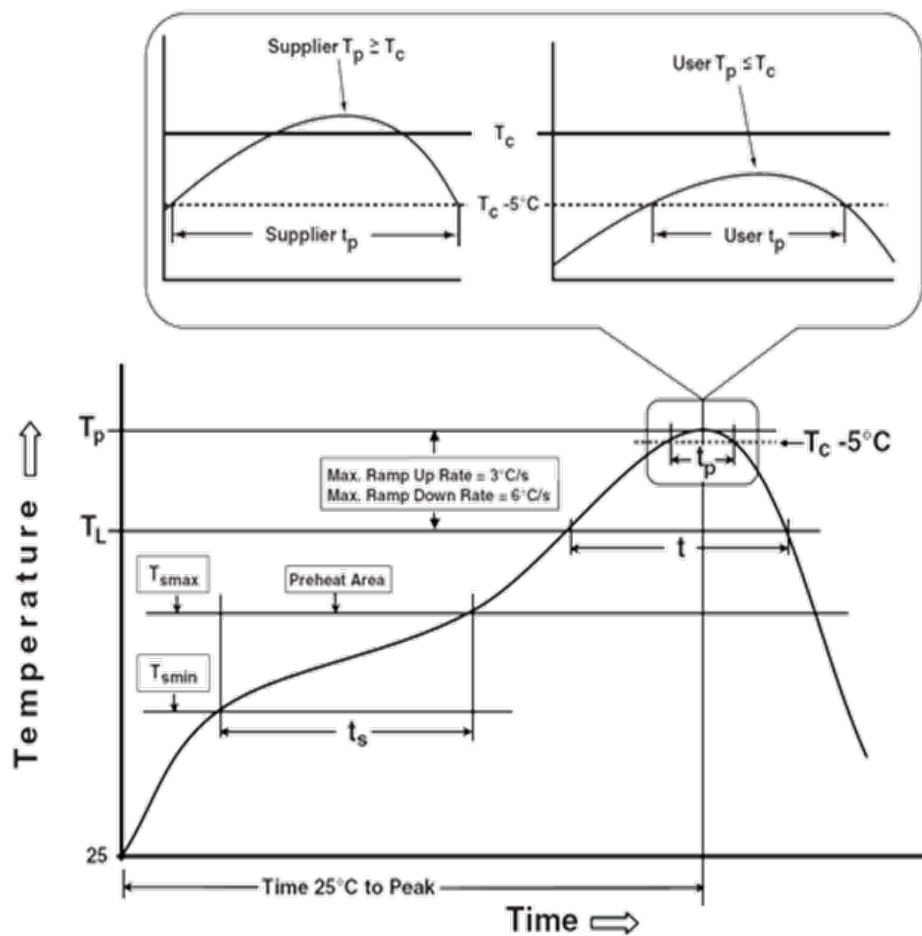
TDFN2x2-6



SOT-23-5



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat & Soak		
Temperature min (T_{smin})	100 °C	150 °C
Temperature max (T_{smax})	150 °C	200 °C
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 °C/second max.	3°C/second max.
Liquidous temperature (T_L)	183 °C	217 °C
Time at liquidous (t_L)	60-150 seconds	60-150 seconds
Peak package body Temperature (T_p)*	See Classification Temp in table 1	See Classification Temp in table 2
Time (t_p)** within 5°C of the specified classification temperature (T_c)	20** seconds	30** seconds
Average ramp-down rate (T_p to T_{smax})	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.
* Tolerance for peak profile Temperature (T_p) is defined as a supplier minimum and a user maximum.		
** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.		

Table 1. SnPb Eutectic Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (T_c)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350-2000	Volume mm ³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

Reliability Test Program

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ T_j =125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C
HBM	MIL-STD-883-3015.7	VHBM ≥ 2KV
MM	JESD-22, A115	VMM ≥ 200V
Latch-Up	JESD 78	10ms, $I_{tr} \geq 100mA$

Customer Service

Anpec Electronics Corp.

Head Office :

No.6, Dusing 1st Road, SBIP,

Hsin-Chu, Taiwan, R.O.C.

Tel : 886-3-5642000

Fax : 886-3-5642050

Taipei Branch :

2F, No. 11, Lane 218, Sec 2 Jhongsing Rd.,

Sindian City, Taipei County 23146, Taiwan

Tel : 886-2-2910-3838

Fax : 886-2-2917-3838